

ONE SOURCE ONE SOLUTION



Die & Wafer Solutions



- Largest Global Die Distributor
- Next-Gen Materials: GaN, SiC
- Die Express Quick Turn Service
- Turnkey Wafer Processing: Wafer Thinning & Dicing, Pick & Place, Wafer Probe, Mapping & Inking, Visual Inspection
- Customized Output: Sawn on Foil, Waffle Pack, Gel-Pak, Tape & Reel
- Vendor Managed Inventory, Long Term Die & Wafer Storage
- EOL Die Sustainment Program
- Lot Acceptance Testing & Element Evaluation

Hi-Rel Products



- Memory, MIL-STD-1553, Logic, RF/Microwave
- Hi-Rel Power: DC-DC Hybrids & PCBs, Diodes
- Couplers & Harness Assemblies
- QML/SMD 5962, MIL-PRF-19500, MIL-PRF-38535, MIL-PRF-38534
- Hermetic: DIP, SOJ, LCC, FP, QFP, Gull Wing, PGA, Metal Can
- Plastic: CSP, BGA, QFN, ZIP
- Advanced Packaging: Flip-Chip, WLP, SiP, 2.5/3DHI, Chiplets, Novel Microfabrication
- Precision Die Attach to 0.5µm
- Custom ASICs

Testing & Qualification



- Electrical & Environmental Testing
- Device Characterization Testing
- FPGA, ASIC, RF, Memory, Analog, Logic, Mixed Signal & Discrete
- DMEA Trusted Source for Test and Process Screening
- PEMs/COTS Upscreening & Qual, Reliability Testing
- Advanced Chamberless Burn-In, HTOL/TOL
- ESD Characterization
- Acoustic Microscopy, X-Ray, XRF, PIND, Fine/Gross Leak Testing
- Counterfeit Mitigation Services

Component Modification



- Robotic Hot Solder Dip
- BGA Reballing
- CGA Attach
- Component Prep. & Lead Attach
- Trim & Form, and Reconditioning
- Component Harvesting
- Support Solutions: Tape & Reel, Marking, Labeling & Kitting, Bake & Package, IC Program, 3D Scan
- Supplier Managed Inventory (SMI)
- Serving All Standard Package Types
- NADCAP Certified



Original Qualified Product

With access to the broadest supply of die, we will source originally qualified parts that have or will become EOL, avoiding costly requalification.

Form-Fit-Function Recreation

When original qualified die or components are not available, Micross has the expertise to reverse engineer devices and recreate equivalent devices.

Program Sustainment Management

Uninterrupted product supply through BOM monitoring, long term die & wafer storage and turnkey and supplier managed inventory



Facilities & Locations

18 World Class Manufacturing Operations (650,000+ ft²) in North America & Europe. AS9100 & ISO9001 Certified.

Die & Wafer Solutions



Apopka, FL

Die & Wafer Solutions

Wafer Processing & Test, Bare Die & Wafer Distribution



Los Alamitos, CA

SemiDice

Wafer Processing & Test, Bare Die & Wafer Distribution



Milpitas, CA

Integra Technologies

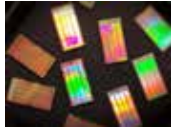
Wafer Processing & Test



Norwich, UK

Die & Wafer Solutions

Wafer Processing & Test, Bare Die & Wafer Distribution



Woburn, MA

Micross Express

Bare Die & Wafer Distribution, Passive Components, Same-Day Service, & Vendor Managed Inventory

Hi-Rel Power Solutions



San Jose, CA

Hi-Rel Power Solutions

Hybrid DC-DC Converters and EMI Filters



Ballerup, DK

Hi-Rel Power Solutions

COTS and Custom Board-Based Power Products



Reynosa, MX

Hi-Rel Diodes

Hi-Rel Discrete Diodes and Assemblies (ISOPAC®)

Components & Services



Apopka, FL

Hi-Rel Components

MCM / Hybrid Packaging, Assembly, Test and Hi-Rel Products



Clearwater, FL

Counterfeit Mitigation

Counterfeit Detection Testing, Upscreening, and IC Programming



Milpitas, CA

Silicon Turnkey Solutions

Electrical and Reliability Test, COTS/PEMs Upscreening & Qualification



Milpitas, CA

Integra Technologies

Assembly, Electrical and Reliability Test, Electrical and RF Testing, and Qualification & Screening



Portsmouth, UK

Hi-Rel Components

MCM / Hybrid Packaging, Assembly, Test, and Hi-Rel Products



Raleigh, NC

Adv. Interconnect Technology

2.5/3D Heterogeneous Integration & Wafer Level Packaging (WLP)



Shirley, MA

Hi-Rel RF Solutions

GaN / GaAs RF and Microwave Switches, Amplifiers, & Attenuators



Sunrise, FL

Couplers & Harnesses

Hi-Rel MIL-STD-1553 Data Bus Couplers and Harness Assemblies



Wichita, KS

Integra Technologies

Electrical and Reliability Test, Counterfeit Detection Testing and Screening

Component Modification Services



Manchester, NH

Component Modification

Robotic Hot Solder Dip (RHSD), Lead Attach, and Trim & Form



Round Rock, TX

Component Modification

BGA Reballing, Components Harvesting, and Solderability



Crewe, UK

Component Modification

Robotic Hot Solder Dip (RHSD), TCE, BGA Reballing, CGA, and Plating

Corporate Headquarters



Melville, NY

Micross Headquarters

Engineering & Program Management Support

Micross' highly experienced global field sales, and expert engineering teams provide complete application support from design specification to post production sustainment & program management.

Micross Heritage

With Over 45+ Years Experience, Micross has Strengthened it's Capabilities to Offer the Broadest Microelectronic Solutions Available from One Source.



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